



**THE DATASHEET OF
DS90CF384MTDX**



DS90C383

DS90C383/DS90CF384 +3.3V Programmable LVDS Transmitter 24-Bit Flat Panel Display (FPD) Link-65 MHz, +3.3V LVDS Receiver 24-Bit Flat Panel Display (FPD) Link-65 MHz



Literature Number: SNLS124A

DS90C383/DS90CF384 +3.3V Programmable LVDS Transmitter 24-Bit Flat Panel Display (FPD) Link—65 MHz, +3.3V LVDS Receiver 24-Bit Flat Panel Display (FPD) Link—65 MHz

General Description

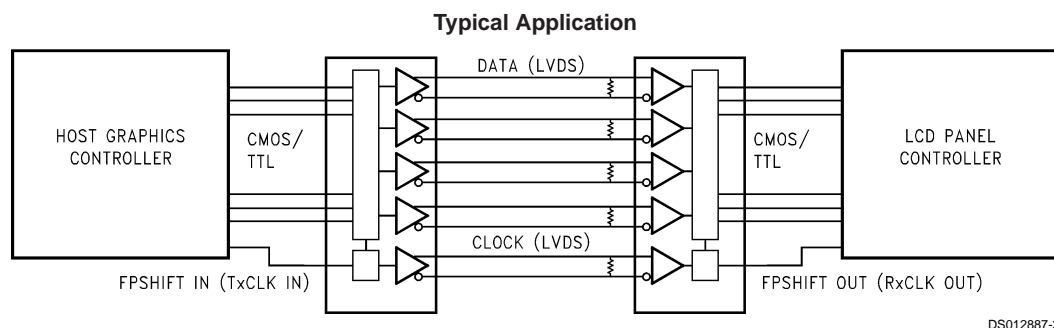
The DS90C383 transmitter converts 28 bits of LVCMOS/LVTTL data into four LVDS (Low Voltage Differential Signaling) data streams. A phase-locked transmit clock is transmitted in parallel with the data streams over a fifth LVDS link. Every cycle of the transmit clock 28 bits of input data are sampled and transmitted. The DS90CF384 receiver converts the LVDS data streams back into 28 bits of LVCMOS/LVTTL data. At a transmit clock frequency of 65 MHz, 24 bits of RGB data and 3 bits of LCD timing and control data (FPLINE, FPFRAME, DRDY) are transmitted at a rate of 455 Mbps per LVDS data channel. Using a 65 MHz clock, the data throughputs is 227 Mbytes/sec. The transmitter is offered with programmable edge data strobes for convenient interface with a variety of graphics controllers. The transmitter can be programmed for Rising edge strobe or Falling edge strobe through a dedicated pin. A Rising edge transmitter will inter-operate with a Falling edge receiver (DS90CF384) without any translation logic. Both devices are also offered in a 64 ball, 0.8mm fine pitch ball grid array (FBGA) package which provides a 44 % reduction in PCB footprint compared to the TSSOP package.

This chipset is an ideal means to solve EMI and cable size problems associated with wide, high speed TTL interfaces.

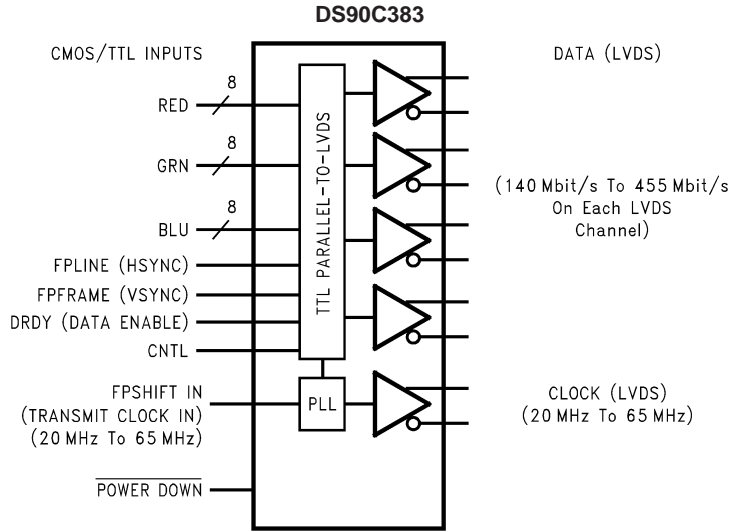
Features

- 20 to 65 MHz shift clock support
- Programmable transmitter (DS90C383) strobe select (Rising or Falling edge strobe)
- Single 3.3V supply
- Chipset (Tx + Rx) power consumption < 250 mW (typ)
- Power-down mode (< 0.5 mW total)
- Single pixel per clock XGA (1024x768) ready
- Supports VGA, SVGA, XGA and higher addressability.
- Up to 227 Megabytes/sec bandwidth
- Up to 1.8 Gbps throughput
- Narrow bus reduces cable size and cost
- 290 mV swing LVDS devices for low EMI
- PLL requires no external components
- Low profile 56-lead TSSOP package.
- Also available in a 64 ball, 0.8mm fine pitch ball grid array (FBGA) package
- Falling edge data strobe Receiver
- Compatible with TIA/EIA-644 LVDS standard
- ESD rating >7 kV
- Operating Temperature: -40°C to +85°C

Block Diagrams

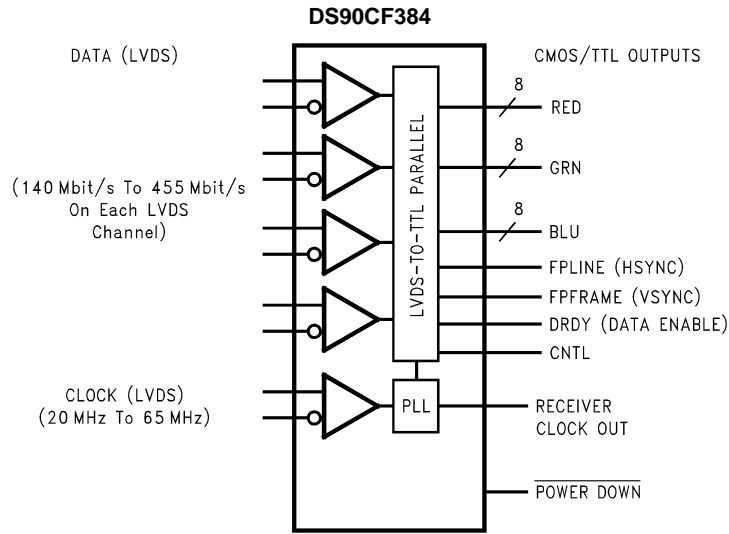


Block Diagrams (Continued)



DS012887-1

Order Number DS90C383MTD or DS90C383SLC
See NS Package Number MTD56 or SLC64A



DS012887-24

Order Number DS90CF384MTD or DS90CF384SLC
See NS Package Number MTD56 or SLC64A

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

| | |
|---|------------------------------|
| Supply Voltage (V_{CC}) | -0.3V to +4V |
| CMOS/TTL Input Voltage | -0.3V to ($V_{CC} + 0.3V$) |
| CMOS/TTL Output Voltage | -0.3V to ($V_{CC} + 0.3V$) |
| LVDS Receiver Input Voltage | -0.3V to ($V_{CC} + 0.3V$) |
| LVDS Driver Output Voltage | -0.3V to ($V_{CC} + 0.3V$) |
| LVDS Output Short Circuit Duration | Continuous |
| Junction Temperature | +150°C |
| Storage Temperature | -65°C to +150°C |
| Lead Temperature (Soldering, 4 sec for TSSOP) | +260°C |
| Solder Reflow Temperature (20 sec for FBGA) | +220°C |
| Maximum Package Power Dissipation Capacity 25°C | |
| MTD56 (TSSOP) Package: | |
| DS90C383MTD | 1.63 W |
| DS90CF384MTD | 1.61 W |
| Package Derating: | |
| DS90C383MTD | 12.5 mW/°C above +25°C |

| | |
|---|------------------------|
| DS90CF384MTD | 12.4 mW/°C above +25°C |
| Maximum Package Power Dissipation Capacity 25°C | |
| SLC64A Package: | |
| DS90C383SLC | 2.0 W |
| DS90CF384SLC | 2.0 W |
| Package Derating: | |
| DS90C383SLC | 10.2 mW/°C above +25°C |
| DS90CF384SLC | 10.2 mW/°C above +25°C |

| | |
|---|--------|
| ESD Rating (HBM, 1.5 k Ω , 100 pF) | > 7 kV |
|---|--------|

Recommended Operating Conditions

| | Min | Nom | Max | Units |
|--|-----|-----|-----|------------------|
| Supply Voltage (V_{CC}) | 3.0 | 3.3 | 3.6 | V |
| Operating Free Air Temperature (T_A) | -40 | +25 | +85 | °C |
| Receiver Input Range | 0 | | 2.4 | V |
| Supply Noise Voltage (V_{CC}) | | | 100 | mV _{PP} |

Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Units | |
|--|--|--|--------------|-----------|----------|---------|----|
| LVC MOS/LVTTL DC SPECIFICATIONS | | | | | | | |
| V_{IH} | High Level Input Voltage | | 2.0 | | V_{CC} | V | |
| V_{IL} | Low Level Input Voltage | | GND | | 0.8 | V | |
| V_{OH} | High Level Output Voltage | $I_{OH} = -0.4$ mA | 2.7 | 3.3 | | V | |
| V_{OL} | Low Level Output Voltage | $I_{OL} = 2$ mA | | 0.06 | 0.3 | V | |
| V_{CL} | Input Clamp Voltage | $I_{CL} = -18$ mA | | -0.79 | -1.5 | V | |
| I_{IN} | Input Current | $V_{IN} = V_{CC}, GND, 2.5V$ or 0.4V | | ± 5.1 | ± 10 | μA | |
| I_{OS} | Output Short Circuit Current | $V_{OUT} = 0V$ | | -60 | -120 | mA | |
| LVDS DC SPECIFICATIONS | | | | | | | |
| V_{OD} | Differential Output Voltage | $R_L = 100\Omega$ | 250 | 345 | 450 | mV | |
| ΔV_{OD} | Change in V_{OD} between complimentary output states | | | | 35 | mV | |
| V_{OS} | Offset Voltage (Note 4) | | 1.125 | 1.25 | 1.375 | V | |
| ΔV_{OS} | Change in V_{OS} between complimentary output states | | | | 35 | mV | |
| I_{OS} | Output Short Circuit Current | $V_{OUT} = 0V, R_L = 100\Omega$ | | -3.5 | -5 | mA | |
| I_{OZ} | Output TRI-STATE® Current | Power Down = 0V, $V_{OUT} = 0V$ or V_{CC} | | ± 1 | ± 10 | μA | |
| V_{TH} | Differential Input High Threshold | $V_{CM} = +1.2V$ | | | +100 | mV | |
| V_{TL} | Differential Input Low Threshold | | -100 | | | mV | |
| I_{IN} | Input Current | $V_{IN} = +2.4V, V_{CC} = 3.6V$ | | | ± 10 | μA | |
| | | $V_{IN} = 0V, V_{CC} = 3.6V$ | | | ± 10 | μA | |
| TRANSMITTER SUPPLY CURRENT | | | | | | | |
| ICCTW | Transmitter Supply Current | $R_L = 100\Omega,$ $C_L = 5$ pF, | f = 32.5 MHz | | 31 | 45 | mA |
| | Worst Case | Worst Case Pattern | f = 37.5 MHz | | 32 | 50 | mA |

Electrical Characteristics (Continued)

Over recommended operating supply and temperature ranges unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Units | |
|-----------------------------------|--|---|-----------------------|-----|-----|---------------|----|
| TRANSMITTER SUPPLY CURRENT | | | | | | | |
| | | (Figures 1, 3), $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | $f = 65\text{ MHz}$ | | 42 | 55 | mA |
| ICCTG | Transmitter Supply Current 16 Grayscale | $R_L = 100\Omega$, $C_L = 5\text{ pF}$, 16 Grayscale Pattern (Figures 2, 3), $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | $f = 32.5\text{ MHz}$ | | 23 | 35 | mA |
| | | | $f = 37.5\text{ MHz}$ | | 28 | 40 | mA |
| | | | $f = 65\text{ MHz}$ | | 31 | 45 | mA |
| ICCTZ | Transmitter Supply Current Power Down | Power Down = Low Driver Outputs in TRI-STATE® under Power Down Mode | | 10 | 55 | μA | |
| RECEIVER SUPPLY CURRENT | | | | | | | |
| ICCRW | Receiver Supply Current Worst Case | $C_L = 8\text{ pF}$, Worst Case Pattern (Figures 1, 4), $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | $f = 32.5\text{ MHz}$ | | 49 | 65 | mA |
| | | | $f = 37.5\text{ MHz}$ | | 53 | 70 | mA |
| | | | $f = 65\text{ MHz}$ | | 78 | 105 | mA |
| ICCRG | Receiver Supply Current, 16 Grayscale | $C_L = 8\text{ pF}$, 16 Grayscale Pattern (Figures 2, 4), $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | $f = 32.5\text{ MHz}$ | | 28 | 45 | mA |
| | | | $f = 37.5\text{ MHz}$ | | 30 | 47 | mA |
| | | | $f = 65\text{ MHz}$ | | 43 | 60 | mA |
| ICCRZ | Receiver Supply Current Power Down | Power Down = Low Receiver Outputs Stay Low during Power Down Mode | | 10 | 55 | μA | |

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.

Note 2: Typical values are given for $V_{CC} = 3.3\text{V}$ and $T_A = +25^\circ\text{C}$.

Note 3: Current into device pins is defined as positive. Current out of device pins is defined as negative. Voltages are referenced to ground unless otherwise specified (except V_{OD} and ΔV_{OD}).

Note 4: V_{OS} previously referred as V_{CM} .

Transmitter Switching Characteristics

Over recommended operating supply and $-40^\circ\text{C to } +85^\circ\text{C}$ ranges unless otherwise specified

| Symbol | Parameter | Min | Typ | Max | Units | |
|--------|--|---------------------|------|-------|-------|----|
| LLHT | LVDS Low-to-High Transition Time (Figure 3) | | 0.75 | 1.5 | ns | |
| LHLT | LVDS High-to-Low Transition Time (Figure 3) | | 0.75 | 1.5 | ns | |
| TCIT | TxCLK IN Transition Time (Figure 5) | | | 5 | ns | |
| TCCS | TxOUT Channel-to-Channel Skew (Figure 6) | | 250 | | ps | |
| TPPos0 | Transmitter Output Pulse Position for Bit 0 (Figure 17) | $f = 65\text{ MHz}$ | -0.4 | 0 | 0.3 | ns |
| TPPos1 | Transmitter Output Pulse Position for Bit 1 | | 1.8 | 2.2 | 2.5 | ns |
| TPPos2 | Transmitter Output Pulse Position for Bit 2 | | 4.0 | 4.4 | 4.7 | ns |
| TPPos3 | Transmitter Output Pulse Position for Bit 3 | | 6.2 | 6.6 | 6.9 | ns |
| TPPos4 | Transmitter Output Pulse Position for Bit 4 | | 8.4 | 8.8 | 9.1 | ns |
| TPPos5 | Transmitter Output Pulse Position for Bit 5 | | 10.6 | 11 | 11.3 | ns |
| TPPos6 | Transmitter Output Pulse Position for Bit 6 | | 12.8 | 13.2 | 13.5 | ns |
| TCIP | TxCLK IN Period (Figure 7) | 15 | T | 50 | ns | |
| TCIH | TxCLK IN High Time (Figure 7) | 0.35T | 0.5T | 0.65T | ns | |
| TCIL | TxCLK IN Low Time (Figure 7) | 0.35T | 0.5T | 0.65T | ns | |
| TSTC | TxIN Setup to TxCLK IN (Figure 7) | $f = 65\text{ MHz}$ | 2.5 | | | ns |
| THTC | TxIN Hold to TxCLK IN (Figure 7) | | 0 | | | ns |
| TCCD | TxCLK IN to TxCLK OUT Delay 25°C , $V_{CC} = 3.3\text{V}$ (Figure 9) | 3.0 | 3.7 | 5.5 | ns | |

Transmitter Switching Characteristics (Continued)

Over recommended operating supply and -40°C to $+85^{\circ}\text{C}$ ranges unless otherwise specified

| Symbol | Parameter | Min | Typ | Max | Units |
|--------|---|-----|-----|-----|-------|
| TPLLS | Transmitter Phase Lock Loop Set (Figure 11) | | | 10 | ms |
| TPDD | Transmitter Power Down Delay (Figure 15) | | | 100 | ns |

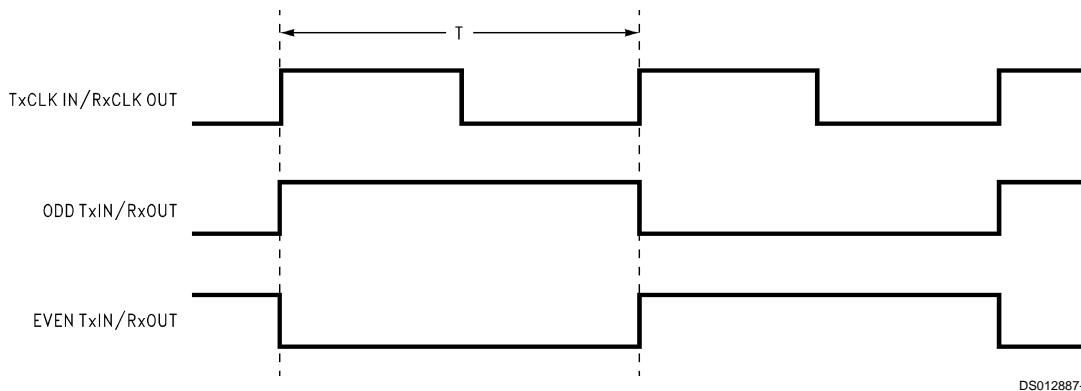
Receiver Switching Characteristics

Over recommended operating supply and -40°C to $+85^{\circ}\text{C}$ ranges unless otherwise specified

| Symbol | Parameter | Min | Typ | Max | Units | | |
|--------|--|------------|-----|------|---------------|------|----|
| CLHT | CMOS/TTL Low-to-High Transition Time (Figure 4) | | 2.2 | 5.0 | ns | | |
| CHLT | CMOS/TTL High-to-Low Transition Time (Figure 4) | | 2.2 | 5.0 | ns | | |
| RSPos0 | Receiver Input Strobe Position for Bit 0 (Figure 18) | f = 65 MHz | | 0.7 | 1.1 | 1.4 | ns |
| RSPos1 | Receiver Input Strobe Position for Bit 1 | | | 2.9 | 3.3 | 3.6 | ns |
| RSPos2 | Receiver Input Strobe Position for Bit 2 | | | 5.1 | 5.5 | 5.8 | ns |
| RSPos3 | Receiver Input Strobe Position for Bit 3 | | | 7.3 | 7.7 | 8.0 | ns |
| RSPos4 | Receiver Input Strobe Position for Bit 4 | | | 9.5 | 9.9 | 10.2 | ns |
| RSPos5 | Receiver Input Strobe Position for Bit 5 | | | 11.7 | 12.1 | 12.4 | ns |
| RSPos6 | Receiver Input Strobe Position for Bit 6 | | | 13.9 | 14.3 | 14.6 | ns |
| RSKM | RxIN Skew Margin (Note 5) (Figure 19) | f = 65 MHz | | 400 | | ps | |
| RCOP | RxCLK OUT Period (Figure 8) | 15 | T | 50 | ns | | |
| RCOH | RxCLK OUT High Time (Figure 8) | f = 65 MHz | | 7.3 | 8.6 | | ns |
| RCOL | RxCLK OUT Low Time (Figure 8) | | | 3.45 | 4.9 | | ns |
| RSRC | RxOUT Setup to RxCLK OUT (Figure 8) | | | 2.5 | 6.9 | | ns |
| RHRC | RxOUT Hold to RxCLK OUT (Figure 8) | | | 2.5 | 5.7 | | ns |
| RCCD | RxCLK IN to RxCLK OUT Delay 25°C , $V_{\text{CC}} = 3.3\text{V}$ (Figure 10) | 5.0 | 7.1 | 9.0 | ns | | |
| RPLLS | Receiver Phase Lock Loop Set (Figure 12) | | | 10 | ms | | |
| RPDD | Receiver Power Down Delay (Figure 16) | | | 1 | μs | | |

Note 5: Receiver Skew Margin is defined as the valid data sampling region at the receiver inputs. This margin takes into account the transmitter pulse positions (min and max) and the receiver input setup and hold time (internal data sampling window-RSPOS). This margin allows for LVDS interconnect skew, inter-symbol interference (both dependent on type/length of cable), and clock jitter (less than 250 ps).

AC Timing Diagrams



DS012887-3

FIGURE 1. "Worst Case" Test Pattern

AC Timing Diagrams (Continued)

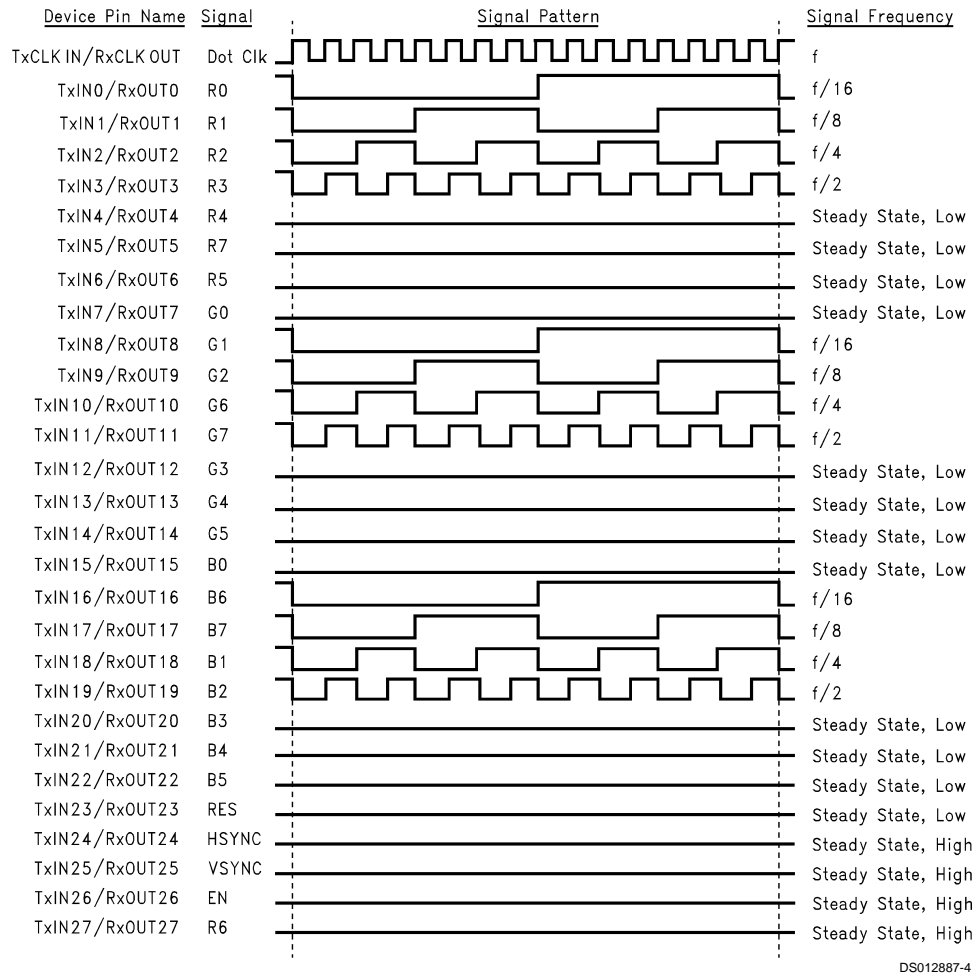


FIGURE 2. "16 Grayscale" Test Pattern (Notes 6, 7, 8, 9)

Note 6: The worst case test pattern produces a maximum toggling of digital circuits, LVDS I/O and CMOS/TTL I/O.

Note 7: The 16 grayscale test pattern tests device power consumption for a "typical" LCD display pattern. The test pattern approximates signal switching needed to produce groups of 16 vertical stripes across the display.

Note 8: Figures 1, 2 show a falling edge data strobe (TxCLK IN/RxCLK OUT).

Note 9: Recommended pin to signal mapping. Customer may choose to define differently.

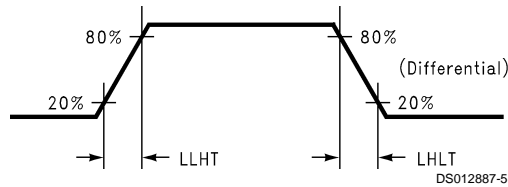


FIGURE 3. DS90C383 (Transmitter) LVDS Output Load and Transition Times

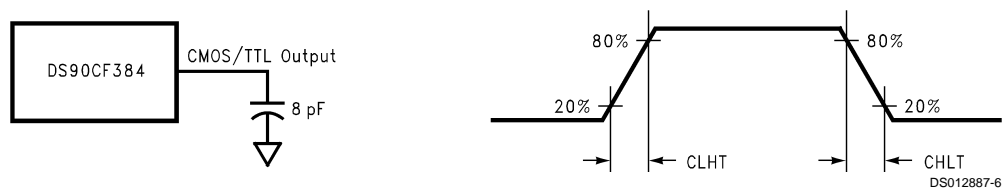


FIGURE 4. DS90CF384 (Receiver) CMOS/TTL Output Load and Transition Times

AC Timing Diagrams (Continued)

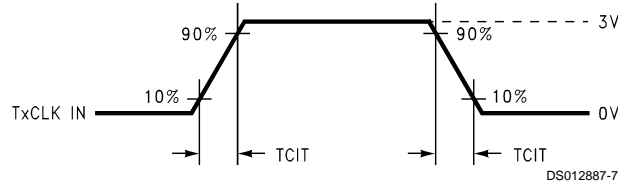
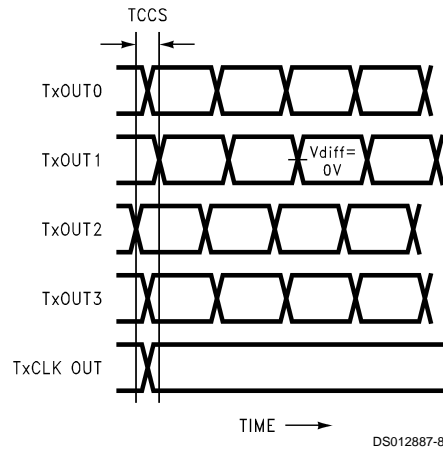


FIGURE 5. DS90C383 (Transmitter) Input Clock Transition Time



Measurements at $V_{diff} = 0V$
 TCCS measured between earliest and latest LVDS edges.
 TxCLK Differential Low \rightarrow High Edge

FIGURE 6. DS90C383 (Transmitter) Channel-to-Channel Skew

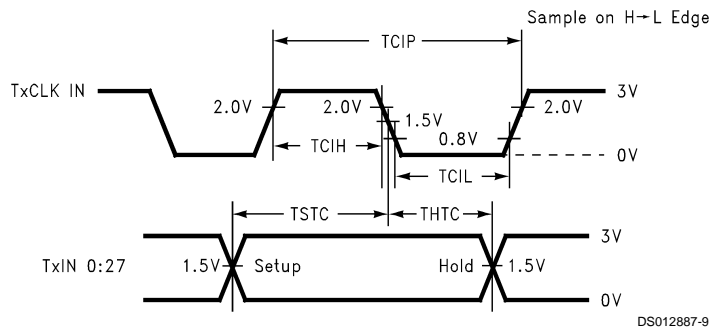


FIGURE 7. DS90C383 (Transmitter) Setup/Hold and High/Low Times (Falling Edge Strobe)

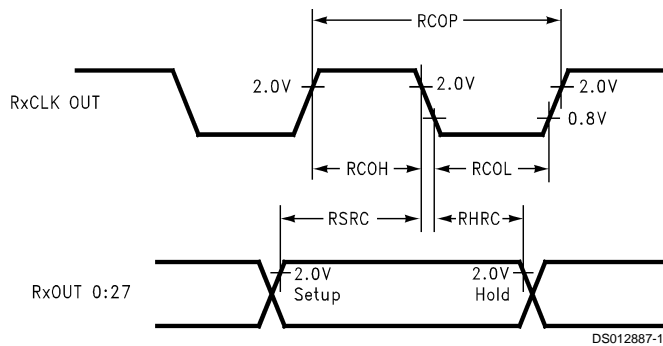


FIGURE 8. DS90CF384 (Receiver) Setup/Hold and High/Low Times

AC Timing Diagrams (Continued)

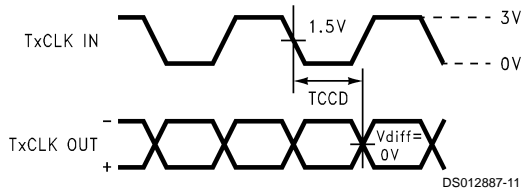


FIGURE 9. DS90C383 (Transmitter) Clock In to Clock Out Delay (Falling Edge Strobe)

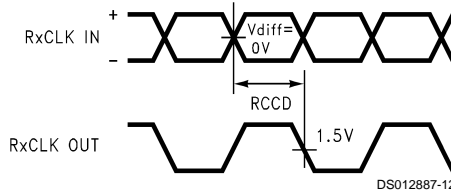


FIGURE 10. DS90CF384 (Receiver) Clock In to Clock Out Delay

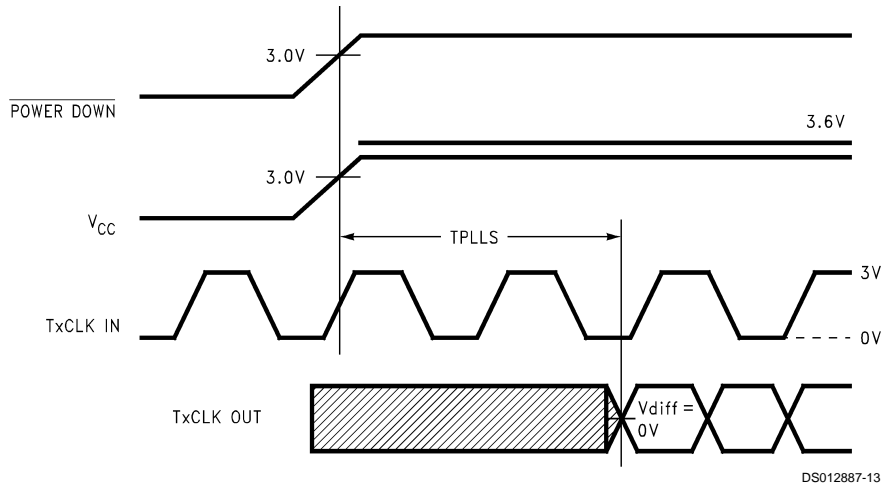


FIGURE 11. DS90C383 (Transmitter) Phase Lock Loop Set Time

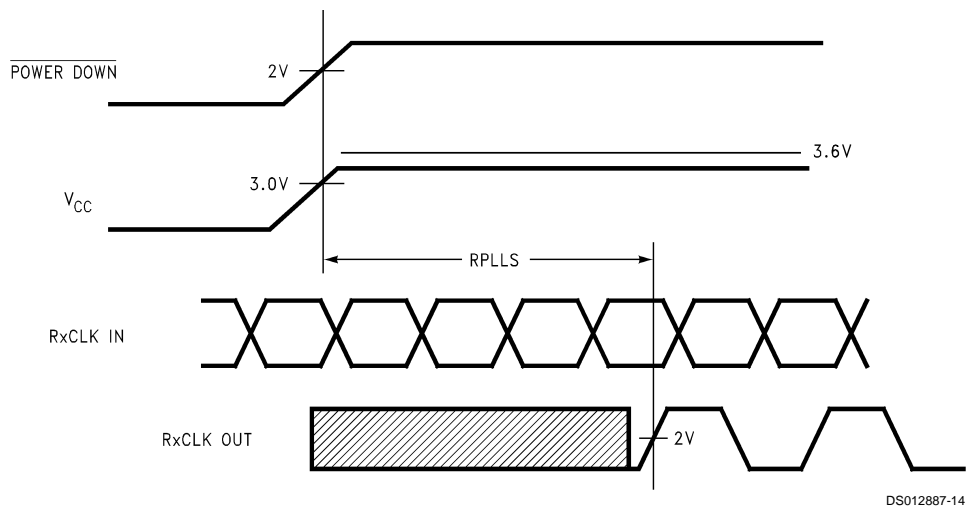
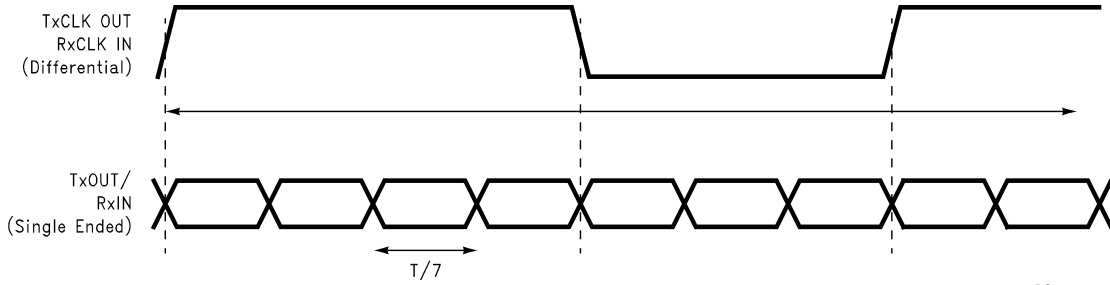


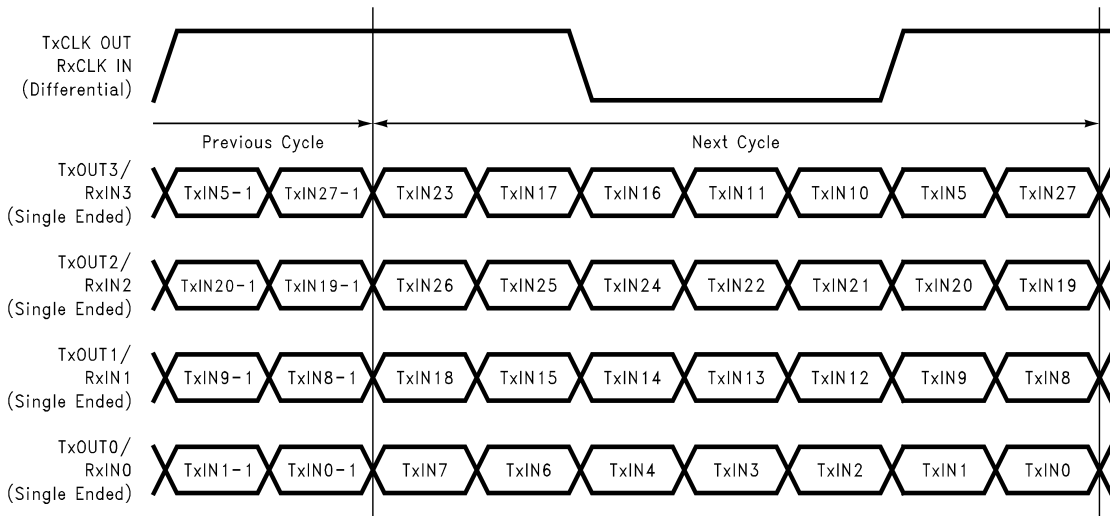
FIGURE 12. DS90CF384 (Receiver) Phase Lock Loop Set Time

AC Timing Diagrams (Continued)



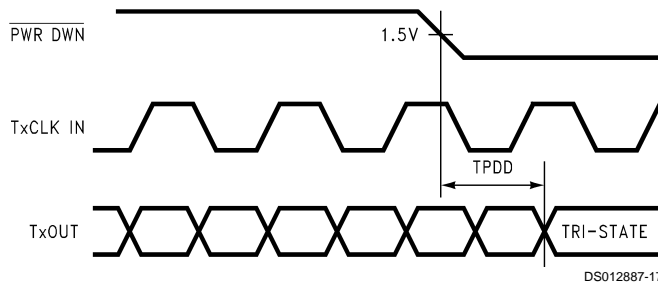
DS012887-15

FIGURE 13. Seven Bits of LVDS in Once Clock Cycle



DS012887-16

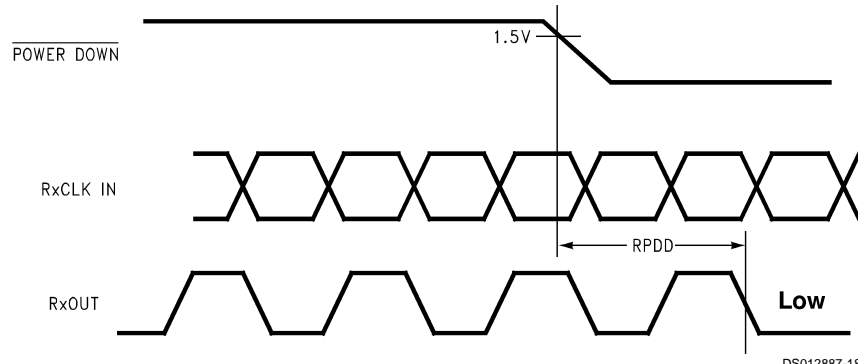
FIGURE 14. 21 Parallel TTL Data Inputs Mapped to LVDS Outputs



DS012887-17

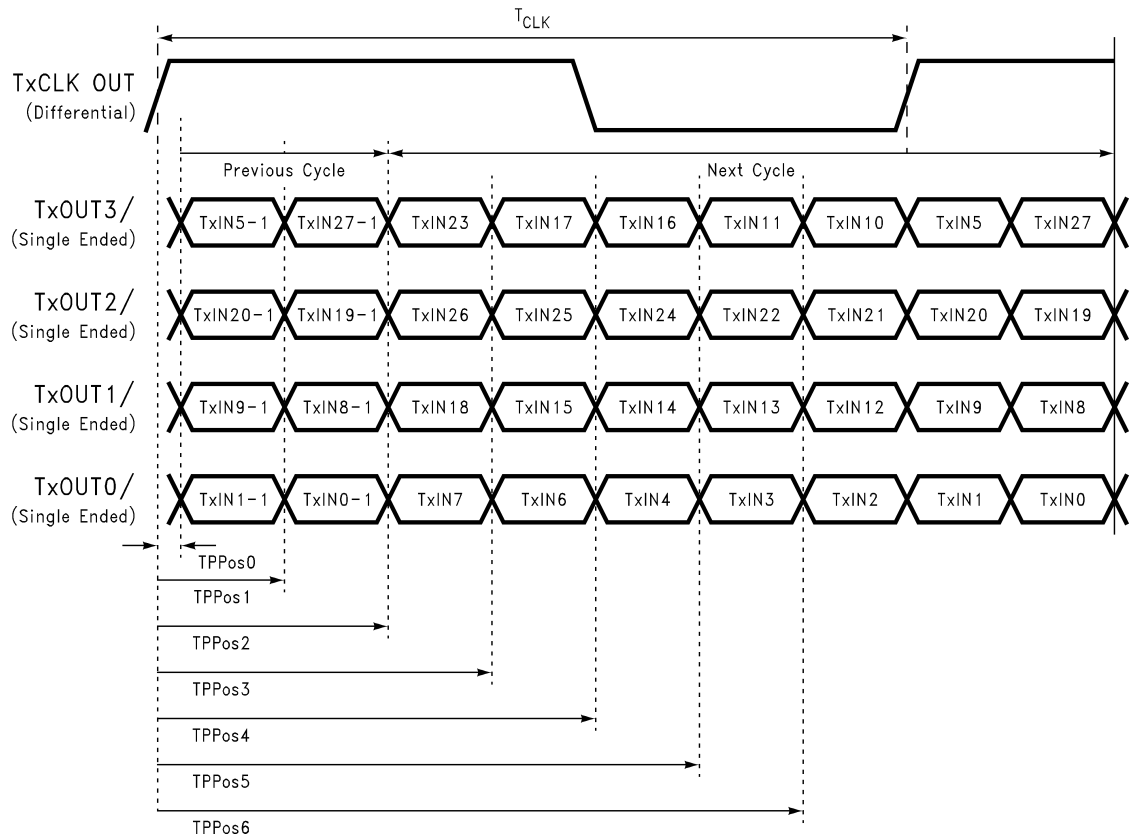
FIGURE 15. Transmitter Power Down Delay

AC Timing Diagrams (Continued)



DS012887-18

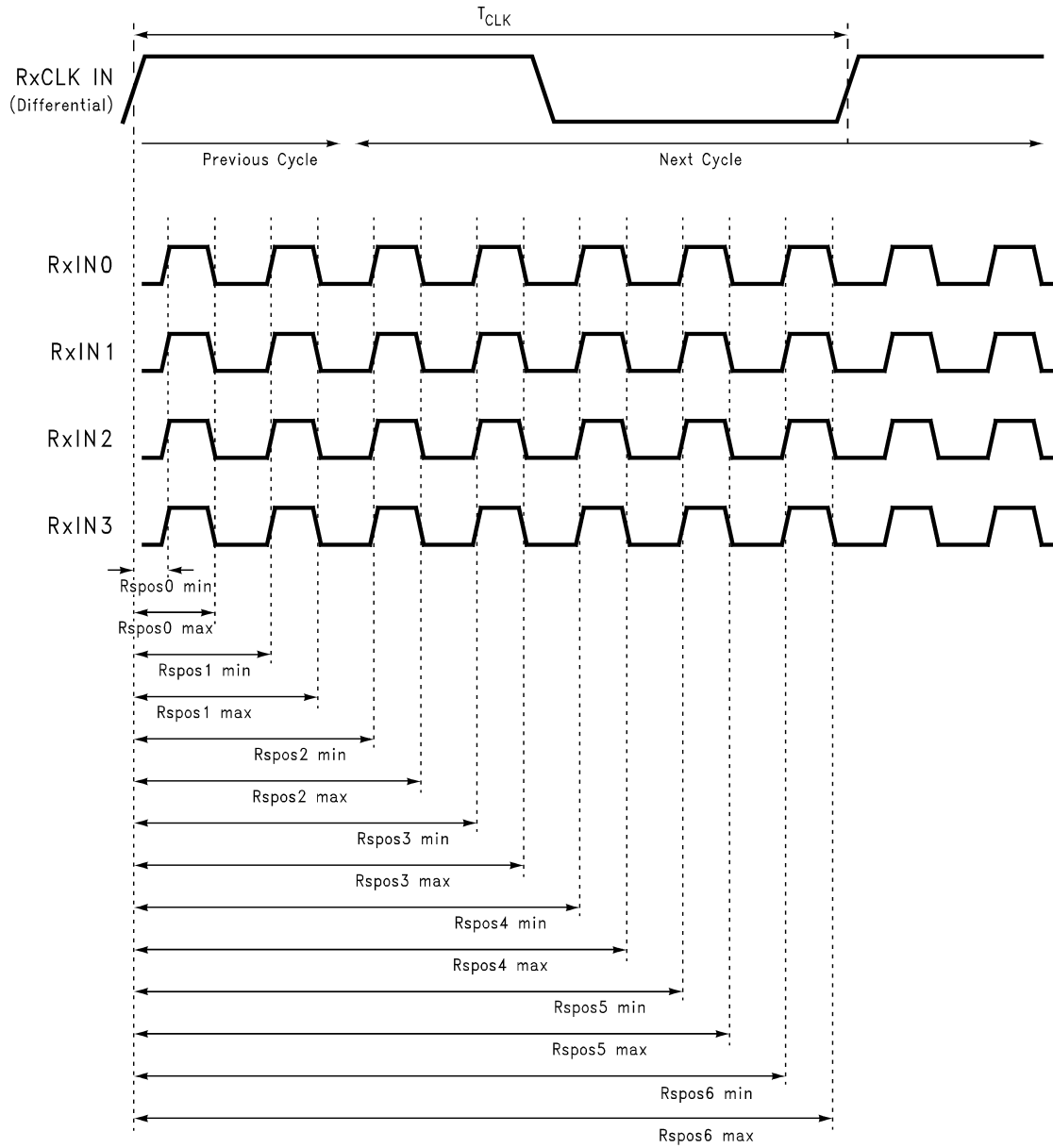
FIGURE 16. Receiver Power Down Delay



DS012887-26

FIGURE 17. Transmitter LVDS Output Pulse Position Measurement

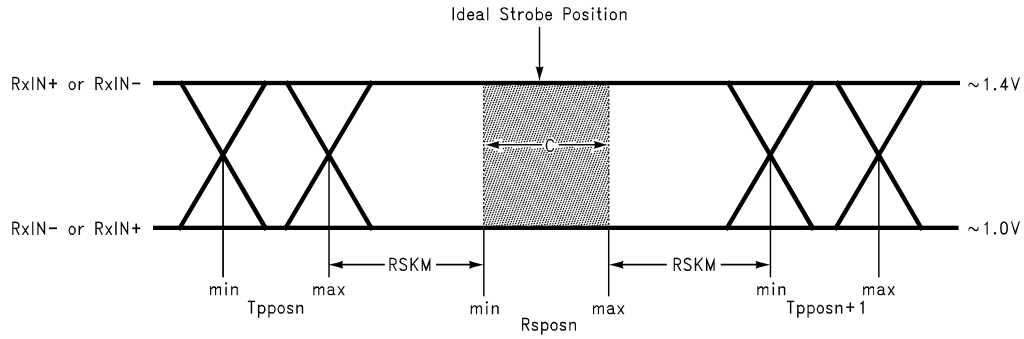
AC Timing Diagrams (Continued)



DS012887-25

FIGURE 18. Receiver LVDS Input Strobe Position

AC Timing Diagrams (Continued)



DS012887-21

C—Setup and Hold Time (Internal data sampling window) defined by Rspos (receiver input strobe position) min and max

Tppos—Transmitter output pulse position (min and max)

RSKM = Cable Skew (type, length) + Source Clock Jitter (cycle to cycle) (Note 10) + ISI (Inter-symbol interference) (Note 11)

Cable Skew—typically 10 ps–40 ps per foot, media dependent

Note 10: Cycle-to-cycle jitter is less than 250 ps at 65 MHz

Note 11: ISI is dependent on interconnect length; may be zero

FIGURE 19. Receiver LVDS Input Skew Margin

Applications Information

The DS90C383 and DS90CF384 are backward compatible with the existing 5V FPD Link transmitter/receiver pair (DS90CR583, DS90CR584, DS90CF583 and DS90CF584). To upgrade from a 5V to a 3.3V system the following must be addressed:

1. Change 5V power supply to 3.3V. Provide this supply to the V_{CC} , LVDS V_{CC} and PLL V_{CC} of both the transmitter and receiver devices. This change may enable the removal of a 5V supply from the system, and power may be supplied from an existing 3V power source.
2. The DS90C383 (transmitter) incorporates a rise/fall strobe select pin. This select function is on pin 17, formerly a V_{CC} connection on the 5V products. When the rise/fall strobe select pin is connected to V_{CC} , the part is configured with a rising edge strobe. In a system currently using a 5V rising edge strobe transmitter (DS90CR583), no layout changes are required to accommodate the new rise/fall select pin on the 3.3V transmitter. The V_{CC} signal may remain at pin 17, and the device will be configured with a rising edge strobe.

When converting from a 5V falling edge transmitter (DS90CF583) to the 3V transmitter a minimal board layout change is necessary. The 3.3V transmitter will not be configured with a falling edge strobe if V_{CC} remains connected to the select pin. To guarantee the 3.3V transmitter functions with a falling edge strobe pin 17 should be connected to ground OR left unconnected. When not connected (left open) and internal pull-down resistor ties pin 17 to ground, thus configuring the transmitter with a falling edge strobe.

3. The DS90C383 transmitter input and control inputs accept 3.3V TTL/CMOS levels. They are not 5V tolerant.

DS90C383 TSSOP Package Pin Description — FPD Link Transmitter

| Pin Name | I/O | No. | Description |
|----------------------|-----|-----|---|
| TxIN | I | 28 | TTL level input. This includes: 8 Red, 8 Green, 8 Blue, and 4 control lines—FPLINE, FPFRAME and DRDY (also referred to as HSYNC, VSYNC, Data Enable). |
| TxOUT+ | O | 4 | Positive LVDS differential data output. |
| TxOUT- | O | 4 | Negative LVDS differential data output. |
| FPSHIFT IN | I | 1 | TTL level clock input. The falling edge acts as data strobe. Pin name TxCLK IN. |
| R_FB | I | 1 | Programmable strobe select. |
| RTxCLK OUT+ | O | 1 | Positive LVDS differential clock output. |
| TxCLK OUT- | O | 1 | Negative LVDS differential clock output. |
| PWR DOWN | I | 1 | TTL level input. When asserted (low input) TRI-STATES the outputs, ensuring low current at power down. |
| V _{CC} | I | 3 | Power supply pins for TTL inputs. |
| GND | I | 4 | Ground pins for TTL inputs. |
| PLL V _{CC} | I | 1 | Power supply pin for PLL. |
| PLL GND | I | 2 | Ground pins for PLL. |
| LVDS V _{CC} | I | 1 | Power supply pin for LVDS outputs. |
| LVDS GND | I | 3 | Ground pins for LVDS outputs. |

DS90C383SLC SLC64A (FBGA) Package Pin Summary — FPD Link Transmitter

| Pin Name | I/O | No. | Description |
|----------------------|-----|-----|--|
| TxIN | I | 28 | TTL level input. |
| TxOUT+ | O | 4 | Positive LVDS differential data output. |
| TxOUT- | O | 4 | Negative LVDS differential data output. |
| TxCLKIN | I | 1 | TTL level clock input. The rising edge acts as data strobe. Pin name TxCLK IN. |
| TxCLK OUT+ | O | 1 | Positive LVDS differential clock output. |
| TxCLK OUT- | O | 1 | Negative LVDS differential clock output. |
| PWR DWN | I | 1 | TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down. |
| R_FB | I | 1 | Programmable strobe select. HIGH = rising edge, LOW = falling edge. |
| V _{CC} | I | 3 | Power supply pins for TTL inputs. |
| GND | I | 5 | Ground pins for TTL inputs. |
| PLL V _{CC} | I | 1 | Power supply pin for PLL. |
| PLL GND | I | 2 | Ground pins for PLL. |
| LVDS V _{CC} | I | 2 | Power supply pin for LVDS outputs. |
| LVDS GND | I | 4 | Ground pins for LVDS outputs. |
| NC | | 6 | Pins not connected. |

DS90C383SLC SLC64A (FBGA) Package Pin Description — FPD Link Transmitter

| By Pin | | | By Pin Type | | |
|--------|-----------|------|-------------|----------|------|
| Pin | Pin Name | Type | Pin | Pin Name | Type |
| A1 | TxIN27 | I | D3 | GND | G |
| A2 | TxOUT0- | O | E4 | GND | G |
| A3 | TxOUT0+ | O | E8 | GND | G |
| A4 | LVDS VCC | P | G1 | GND | G |
| A5 | LVDS VCC | P | G6 | GND | G |
| A6 | TxCLKOUT- | O | B3 | LVDS GND | G |

DS90C383SLC SLC64A (FBGA) Package Pin Description — FPD Link Transmitter (Continued)

| By Pin | | | By Pin Type | | |
|--------|-----------|---|-------------|-----------|---|
| A7 | TxCLKOUT+ | O | B4 | LVDS GND | G |
| A8 | TxOUT3+ | O | B7 | LVDS GND | G |
| B1 | TxIN1 | I | D5 | LVDS GND | G |
| B2 | TxIN0 | I | C6 | PLL GND | G |
| B3 | LVDS GND | G | D6 | PLL GND | G |
| B4 | LVDS GND | G | D7 | PWR DWN | I |
| B5 | TxOUT2- | O | G5 | R_FB | I |
| B6 | TxOUT3- | O | C8 | TxCLKIN | I |
| B7 | LVDS GND | G | B2 | TxIN0 | I |
| B8 | NC | | B1 | TxIN1 | I |
| C1 | TxIN3 | I | D2 | TxIN2 | I |
| C2 | NC | | C1 | TxIN3 | I |
| C3 | NC | | D1 | TxIN4 | I |
| C4 | TxOUT1- | O | F1 | TxIN5 | I |
| C5 | TxOUT2+ | O | E2 | TxIN6 | I |
| C6 | PLL GND | G | E3 | TxIN7 | I |
| C7 | PLL VCC | P | G2 | TxIN8 | I |
| C8 | TxCLKIN | I | H1 | TxIN9 | I |
| D1 | TxIN4 | I | G3 | TxIN10 | I |
| D2 | TxIN2 | I | H3 | TxIN11 | I |
| D3 | GND | G | F4 | TxIN12 | I |
| D4 | TxOUT1+ | O | G4 | TxIN13 | I |
| D5 | LVDS GND | G | H4 | TxIN14 | I |
| D6 | PLL GND | G | H5 | TxIN15 | I |
| D7 | PWR DWN | I | E5 | TxIN16 | I |
| D8 | TxIN26 | I | F5 | TxIN17 | I |
| E1 | VCC | P | H6 | TxIN18 | I |
| E2 | TxIN6 | I | H7 | TxIN19 | I |
| E3 | TxIN7 | I | H8 | TxIN20 | I |
| E4 | GND | G | G7 | TxIN21 | I |
| E5 | TxIN16 | I | F7 | TxIN22 | I |
| E6 | VCC | P | G8 | TxIN23 | I |
| E7 | TxIN24 | I | E7 | TxIN24 | I |
| E8 | GND | G | F8 | TxIN25 | I |
| F1 | TxIN5 | I | D8 | TxIN26 | I |
| F2 | NC | | A1 | TxIN27 | I |
| F3 | NC | | A6 | TxCLKOUT- | O |
| F4 | TxIN12 | I | A7 | TxCLKOUT+ | O |
| F5 | TxIN17 | I | A2 | TxOUT0- | O |
| F6 | NC | | A3 | TxOUT0+ | O |
| F7 | TxIN22 | I | C4 | TxOUT1- | O |
| F8 | TxIN25 | I | D4 | TxOUT1+ | O |
| G1 | GND | G | B5 | TxOUT2- | O |
| G2 | TxIN8 | I | C5 | TxOUT2+ | O |
| G3 | TxIN10 | I | B6 | TxOUT3- | O |
| G4 | TxIN13 | I | A8 | TxOUT3+ | O |
| G5 | R_FB | I | A4 | LVDS VCC | P |
| G6 | GND | G | A5 | LVDS VCC | P |

DS90C383SLC SLC64A (FBGA) Package Pin Description — FPD Link Transmitter (Continued)

| By Pin | | | By Pin Type | | |
|--------|--------|---|-------------|---------|---|
| G7 | TxIN21 | I | C7 | PLL VCC | P |
| G8 | TxIN23 | I | E1 | VCC | P |
| H1 | TxIN9 | I | E6 | VCC | P |
| H2 | VCC | P | H2 | VCC | P |
| H3 | TxIN11 | I | B8 | NC | |
| H4 | TxIN14 | I | C2 | NC | |
| H5 | TxIN15 | I | C3 | NC | |
| H6 | TxIN18 | I | F2 | NC | |
| H7 | TxIN19 | I | F3 | NC | |
| H8 | TxIN20 | I | F6 | NC | |

G : Ground
 I : Input
 O : Output
 P : Power
 NC : No Connect

DS90CF384 MTD56 TSSOP Package Pin Description — FPD Link Receiver

| Pin Name | I/O | No. | Description |
|----------------------|-----|-----|---|
| RxIN+ | I | 4 | Positive LVDS differential data inputs. |
| RxIN- | I | 4 | Negative LVDS differential data inputs. |
| RxOUT | O | 28 | TTL level data outputs. This includes: 8 Red, 8 Green, 8 Blue, and 4 control lines—FPLINE, FPFRAME, DRDY (also referred to as HSYNC, VSYNC, Data Enable). |
| RxCLK IN+ | I | 1 | Positive LVDS differential clock input. |
| RxCLK IN- | I | 1 | Negative LVDS differential clock input. |
| FPSHIFT OUT | O | 1 | TTL level clock output. The falling edge acts as data strobe. Pin name RxCLK OUT. |
| PWR DOWN | I | 1 | TTL level input. When asserted (low input) the receiver outputs are low. |
| V _{CC} | I | 4 | Power supply pins for TTL outputs. |
| GND | I | 5 | Ground pins for TTL outputs. |
| PLL V _{CC} | I | 1 | Power supply for PLL. |
| PLL GND | I | 2 | Ground pin for PLL. |
| LVDS V _{CC} | I | 1 | Power supply pin for LVDS inputs. |
| LVDS GND | I | 3 | Ground pins for LVDS inputs. |

DS90CF384 64 ball FBGA Package Pin Description — FPD Link Receiver

| Pin Name | I/O | No. | Description |
|----------------------|-----|-----|---|
| RxIN+ | I | 4 | Positive LVDS differential data inputs. |
| RxIN- | I | 4 | Negative LVDS differential data inputs. |
| RxOUT | O | 28 | TTL level data outputs. This includes: 8 Red, 8 Green, 8 Blue, and 4 control lines—FPLINE, FPFRAME, DRDY (also referred to as HSYNC, VSYNC, Data Enable). |
| RxCLK IN+ | I | 1 | Positive LVDS differential clock input. |
| RxCLK IN- | I | 1 | Negative LVDS differential clock input. |
| FPSHIFT OUT | O | 1 | TTL level clock output. The falling edge acts as data strobe. Pin name RxCLK OUT. |
| PWR DOWN | I | 1 | TTL level input. When asserted (low input) the receiver outputs are low. |
| V _{CC} | I | 4 | Power supply pins for TTL outputs. |
| GND | I | 5 | Ground pins for TTL outputs. |
| PLL V _{CC} | I | 1 | Power supply for PLL. |
| PLL GND | I | 2 | Ground pin for PLL. |
| LVDS V _{CC} | I | 2 | Power supply pin for LVDS inputs. |

DS90CF384 64 ball FBGA Package Pin Description — FPD Link Receiver

(Continued)

| Pin Name | I/O | No. | Description |
|----------|-----|-----|------------------------------|
| LVDS GND | I | 4 | Ground pins for LVDS inputs. |
| NC | | 6 | Pins not connected. |

DS90CF384 64 ball, FBGA Package Pin Definition — FPD Link Receiver

| By Pin | | | By Pin Type | | |
|--------|----------|------|-------------|----------|------|
| Pin | Pin Name | Type | Pin | Pin Name | Type |
| A1 | RxOUT17 | O | A4 | GND | G |
| A2 | VCC | P | B1 | GND | G |
| A3 | RxOUT15 | O | B6 | GND | G |
| A4 | GND | G | D8 | GND | G |
| A5 | RxOUT12 | O | E3 | GND | G |
| A6 | RxOUT8 | O | E5 | LVDS GND | G |
| A7 | RxOUT7 | O | G3 | LVDS GND | G |
| A8 | RxOUT6 | O | G7 | LVDS GND | G |
| B1 | GND | G | H5 | LVDS GND | G |
| B2 | NC | | F6 | PLL GND | G |
| B3 | RxOUT16 | O | G8 | PLL GND | G |
| B4 | RxOUT11 | O | E6 | PWR DWN | I |
| B5 | VCC | P | H6 | RxCLKIN- | I |
| B6 | GND | G | H7 | RxCLKIN+ | I |
| B7 | RxOUT5 | O | H2 | RxIN0- | I |
| B8 | RxOUT3 | O | H3 | RxIN0+ | I |
| C1 | RxOUT21 | O | F4 | RxIN1- | I |
| C2 | NC | | G4 | RxIN1+ | I |
| C3 | RxOUT18 | O | G5 | RxIN2- | I |
| C4 | RxOUT14 | O | F5 | RxIN2+ | I |
| C5 | RxOUT9 | O | G6 | RxIN3- | I |
| C6 | RxOUT4 | O | H8 | RxIN3+ | I |
| C7 | NC | | E7 | RxCLKOUT | O |
| C8 | RxOUT1 | O | E8 | RxOUT0 | O |
| D1 | VCC | P | C8 | RxOUT1 | O |
| D2 | RxOUT20 | O | D7 | RxOUT2 | O |
| D3 | RxOUT19 | O | B8 | RxOUT3 | O |
| D4 | RxOUT13 | O | C6 | RxOUT4 | O |
| D5 | RxOUT10 | O | B7 | RxOUT5 | O |
| D6 | VCC | P | A8 | RxOUT6 | O |
| D7 | RxOUT2 | O | A7 | RxOUT7 | O |
| D8 | GND | G | A6 | RxOUT8 | O |
| E1 | RxOUT22 | O | C5 | RxOUT9 | O |
| E2 | RxOUT24 | O | D5 | RxOUT10 | O |
| E3 | GND | G | B4 | RxOUT11 | O |
| E4 | LVDS VCC | P | A5 | RxOUT12 | O |
| E5 | LVDS GND | G | D4 | RxOUT13 | O |
| E6 | PWR DWN | I | C4 | RxOUT14 | O |
| E7 | RxCLKOUT | O | A3 | RxOUT15 | O |
| E8 | RxOUT0 | O | B3 | RxOUT16 | O |
| F1 | RxOUT23 | O | A1 | RxOUT17 | O |

DS90CF384 64 ball, FBGA Package Pin Definition — FPD Link Receiver

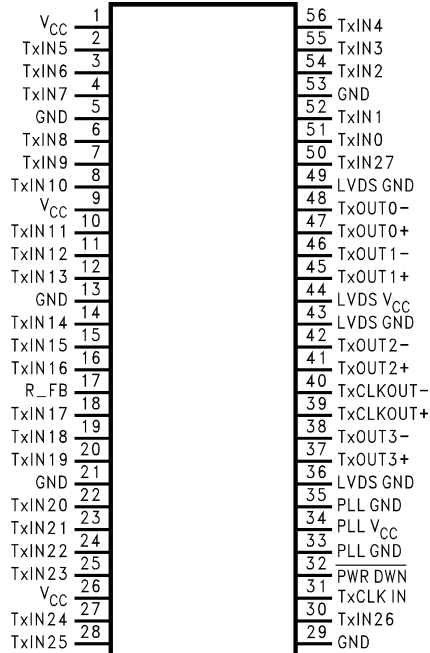
(Continued)

| By Pin | | | By Pin Type | | |
|--------|----------|---|-------------|----------|---|
| F2 | RxOUT26 | O | C3 | RxOUT18 | O |
| F3 | NC | | D3 | RxOUT19 | O |
| F4 | RxIN1- | I | D2 | RxOUT20 | O |
| F5 | RxIN2+ | I | C1 | RxOUT21 | O |
| F6 | PLL GND | G | E1 | RxOUT22 | O |
| F7 | PLL VCC | P | F1 | RxOUT23 | O |
| F8 | NC | | E2 | RxOUT24 | O |
| G1 | RxOUT25 | O | G1 | RxOUT25 | O |
| G2 | NC | | F2 | RxOUT26 | O |
| G3 | LVDS GND | G | H1 | RxOUT27 | O |
| G4 | RxIN1+ | I | E4 | LVDS VCC | P |
| G5 | RxIN2- | I | H4 | LVDS VCC | P |
| G6 | RxIN3- | I | F7 | PLL VCC | P |
| G7 | LVDS GND | G | A2 | VCC | P |
| G8 | PLL GND | G | B5 | VCC | P |
| H1 | RxOUT27 | O | D1 | VCC | P |
| H2 | RxIN0- | I | D6 | VCC | P |
| H3 | RxIN0+ | I | B2 | NC | |
| H4 | LVDS VCC | P | C2 | NC | |
| H5 | LVDS GND | G | C7 | NC | |
| H6 | RxCLKIN- | I | F3 | NC | |
| H7 | RxCLKIN+ | I | F8 | NC | |
| H8 | RxIN3+ | I | G2 | NC | |

G : Ground
 I : Input
 O : Output
 P : Power
 NC : Not Connect

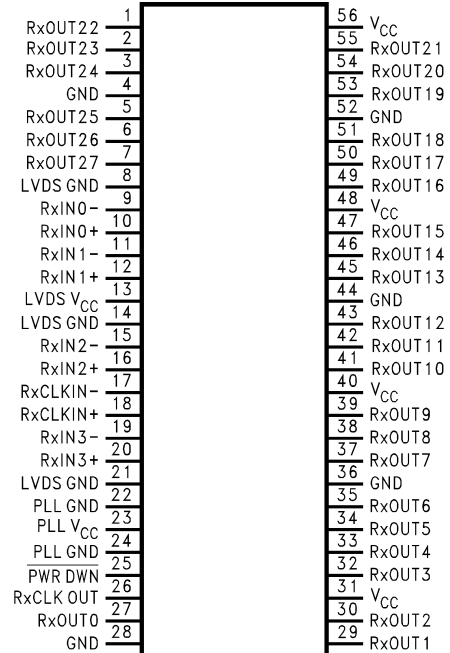
Pin Diagrams for TSSOP Packages

DS90C383MTD



DS012887-22

DS90CF384MTD

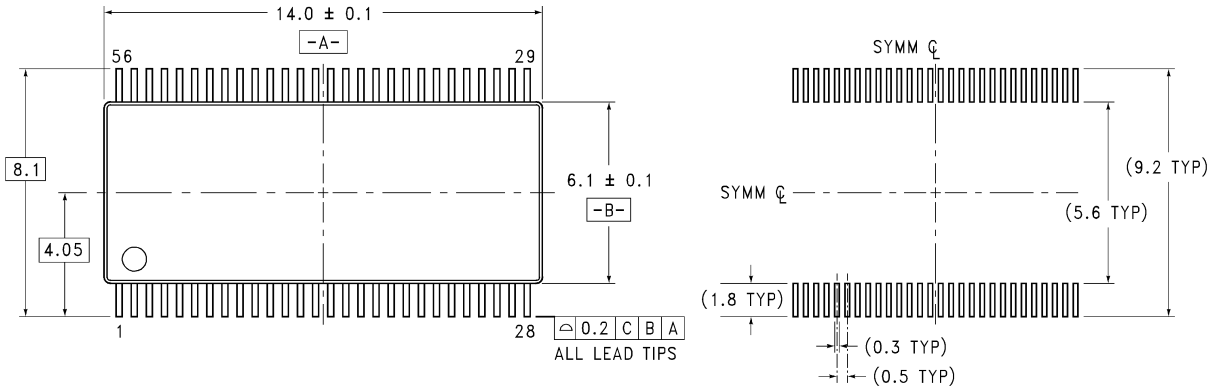


DS012887-23

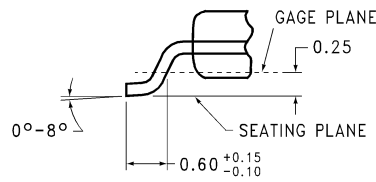
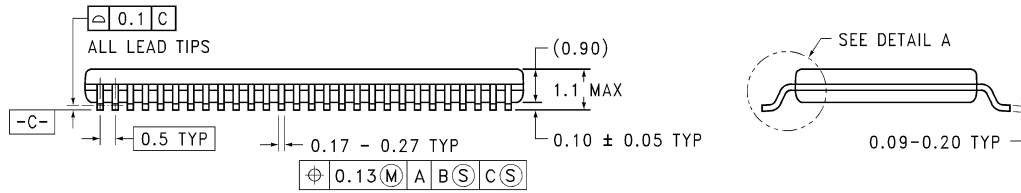
TABLE 1. Programmable Transmitter

| Pin | Condition | Strobe Status |
|------|------------------------|---------------------|
| R_FB | R_FB = V _{CC} | Rising edge strobe |
| R_FB | R_FB = GND | Falling edge strobe |

Physical Dimensions inches (millimeters) unless otherwise noted



LAND PATTERN RECOMMENDATION

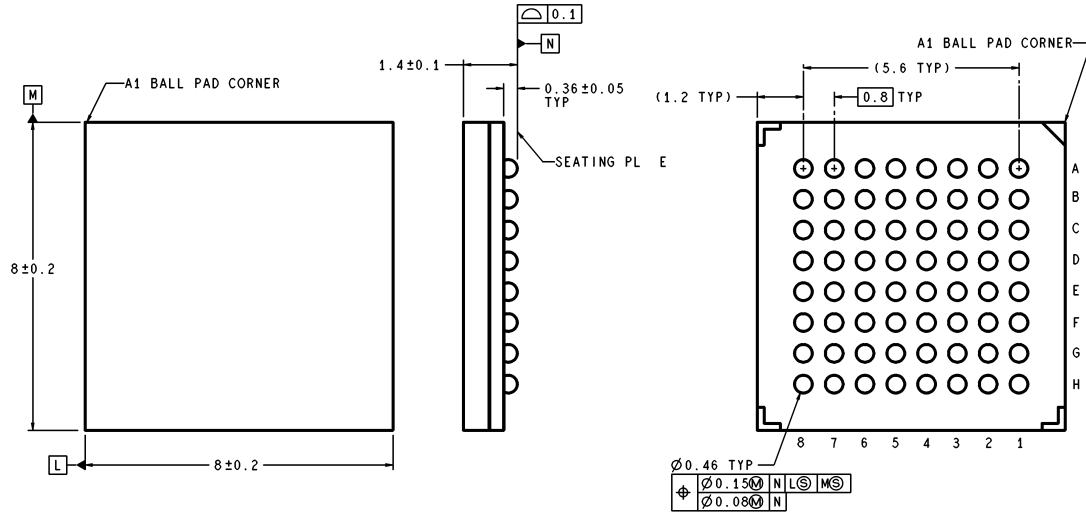


DETAIL A
TYPICAL

MTD56 (REV B)

56-Lead Molded Thin Shrink Small Outline Package, JEDEC
Dimensions show in millimeters
Order Number DS90C383MTD, DS90CF384MTD
NS Package Number MTD56

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

SLC64A (Rev B)

64 ball, 0.8mm fine pitch ball grid array (FBGA) Package
Dimensions show in millimeters only
Order Number DS90CF384SLC or DS90C383SLC
NS Package Number SLC64A

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